



# Attollo Engineering

Document Number:	FRM-020
Document Revision:	001
Approval Date:	3/13/2019

## JOB DESCRIPTION

<b>Job Title:</b>	Focal Plane Array Packaging Engineer	<b>Job Category:</b>	Engineer
<b>Department/Group:</b>	Manufacturing	<b>Job Code:</b>	
<b>Location:</b>	Camarillo, CA	<b>Travel Required:</b>	Infrequent
<b>Level/Salary Range:</b>	Competitive pay BOE	<b>Position Type:</b>	Full Time
<b>HR Contact:</b>		<b>Date posted:</b>	March 29, 2024
<b>Will Train Applicant:</b>	Yes	<b>Posting Expires:</b>	Click here to enter a date.
<b>External posting URL:</b>			

### JOB DESCRIPTION:

Attollo Engineering is a designer and manufacturer of cutting-edge infrared cameras and instruments for defense and industrial applications. Attollo has a full sensor fabricating facility and is a leading supplier of IR sensors in the defense and industrial space. Attollo believes in developing people to provide novel solutions for our customers. Attollo provides competitive salary compensation, a generous insurance package, and 401K matching.

Attollo Engineering is seeking an FPA Packaging Engineer responsible for all back-end manufacturing processing, and post wafer (front-end) processing. Critical areas of responsibility include flip-chip hybridization, Lap & Polish, AR coating, epoxy die bonding and wire-bonding. This role requires qualification and calibration of FPA packaging processes, equipment, and tooling. The ideal candidate has a background in mechanical engineering and IR FPA manufacturing in a cleanroom environment and possesses knowledge of detector and ROIC wafer processing. The successful candidate understands the importance of working as a team, optimizing manufacturing processes, sharing best practices, creating work instructions and training. This role requires the ability to juggle multiple priorities and projects in a fast-paced environment.

#### Role and Responsibilities

- Provide technical leadership in backend processing, including flip-chip hybridization, lap and polish, AR coating, wire-bonding and epoxy die attach/bonding.
- Develop and improve processes focusing on process yield, capability, and throughput.
- Apply knowledge of packaging, semiconductor processing, and device physics to enhance FPA development and innovation.
- Uphold stringent cleanroom manufacturing standards, emphasizing safety, quality, and workflow efficiency.
- Collaborate effectively with cross-functional teams, demonstrating project management skills to drive FPA packaging development projects from concept to completion.
- Maintain rigorous documentation and adhere to industry protocols, ensuring consistent quality and compliance.
- Lead and mentor team members, promoting a results-driven culture of continuous improvement.



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### Qualifications and Education Requirements

- BS or MS in Physics, Material Science, Electrical Engineering, Mechanical Engineering, Industrial Engineering or related fields with a minimum of 3-5+ years
- Expertise in semiconductor packaging, including wire bonding and epoxy die attach/bonding.
- Experience with specialty equipment qualification and calibration; ability to troubleshoot specialty equipment and custom tooling (in coordination with Equipment Engineering).
- Strong excel and data analysis skills; familiarity with data analysis software packages such as JMP is preferred.
- Knowledge of statistical process control (SPC) and six-sigma practices.
- Experience working hands-on in a cleanroom manufacturing environment.
- Proven ability to work in a team-oriented, fast-paced environment, managing multiple priorities and projects with efficiency and reliability.
- Strong analytical skills, detail-oriented, with a commitment to quality and safety
- Proficiency with Microsoft 365 applications, including Excel, Word, and Outlook.
- Excellent communication and interpersonal skills, with the capability to work collaboratively within cross-functional teams.
- Adaptability and flexibility to changing priorities as required.
- Position requires work on DoD contracts, and therefore qualified applications must be US Person (U.S. citizen or green card holder)

### Preferred Skills

- Background in IR FPA Packaging, particularly flip-chip hybridization techniques
- Setting up electronic test equipment and performing device screening
- Knowledge of semiconductor device physics, photodetectors, and FPAs
- Background in semiconductor processing
- Programming experience, Python in particular

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